

Variant: 001
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PMP10750 REV E1 Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	IPCB1	1		PMP10750	Any	Printed Circuit Board	
2	C1, C3	2	4700pF	C0603C472J5RACTU	Kemet	CAP, CERM, 4700 pF, 50 V, +/- 5%, X7R, 0603	0603
3	C2, C10, C11, C12, C26, C27, C28	7	10uF	GRM32ER71H106KA12L	MuRata	CAP, CERM, 10 µF, 50 V, +/- 10%, X7R, 1210	1210
4	C4, C22	2	0.047uF	C1608X7R1E473K	TDK	CAP, CERM, 0.047 µF, 25 V, +/- 10%, X7R, 0603	0603
5	C5, C6, C7, C23	4	1000pF	C0603C102J5RACTU	Kemet	CAP, CERM, 1000 pF, 50 V, +/- 5%, X7R, 0603	0603
6	C8, C9, C24, C25	4	4.7uF	GRM31CR71H475KA12L	MuRata	CAP, CERM, 4.7 µF, 50 V, +/- 10%, X7R, 1206	1206
7	C13, C29	2	0.1uF	06035C104KAT2A	AVX	CAP, CERM, 0.1 µF, 50 V, +/- 10%, X7R, 0603	0603
8	C14, C15, C16, C30, C31, C32	6	22uF	CL10A226MP8NUNE	Samsung Electro-Mechanics	CAP, CERM, 22 µF, 10 V, +/- 20%, X5R, 0603	0603
9	C17, C33	2	3.3uF	C0603C335K9PACTU	Kemet	CAP, CERM, 3.3 µF, 6.3 V, +/- 10%, X5R, 0603	0603
10	C19, C35	2	0.033uF	GRM188R71E333KA01D	MuRata	CAP, CERM, 0.033 µF, 25 V, +/- 10%, X7R, 0603	0603
11	C20, C36	2	0.1uF	06033C104KAT2A	AVX	CAP, CERM, 0.1 µF, 25 V, +/- 10%, X7R, 0603	0603
12	C21	1	2.2uF	GRM188R71A225KE15D	MuRata	CAP, CERM, 2.2 µF, 10 V, +/- 10%, X7R, 0603	0603
13	D1, D2	2	28V	SMBJ28A-13-F	Diodes Inc.	Diode, TVS, Uni, 28 V, 600 W, SMB	SMB
14	D3	1	15V	MMSZ5245BS-7-F	Diodes Inc.	Diode, Zener, 15 V, 200 mW, SOD-323	SOD-323
15	H1, H2, H3, H4	4		NY PMS 440 0025 PH	B&F Fastener Supply	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	Screw
16	H5, H6, H7, H8	4		1902C	Keystone	Standoff, Hex, 0.5"L #4-40 Nylon	Standoff
17	H9, H10, H11, H12	4		SJ-5303 (CLEAR)	3M	Bumpon, Hemisphere, 0.44 X0.20, Clear	Transparent Bumpon
18	J1, J2, J3, J4, J5, J6	6		575-4	Keystone	Standard Banana Jack, Uninsulated, 5.5mm	Keystone_575-4
19	L1, L4	2	2.2uH	74408943022	Würth Elektronik	Inductor, Shielded Drum Core, Ferrite, 2.2 µH, 3 A, 0.026 ohm, SMD	4.8x3.8x4.8mm
20	L2	1		ACM1211-102-2PL-TL01	TDK	Coupled inductor, 6 A, 0.014 ohm, SMD	SMD, 12x11mm
21	L3, L5	2	2.2uH	FDV0630-2R2M	Toko	Inductor, Shielded, Powdered Iron, 2.2 µH, 5.3 A, 0.021 ohm, SMD	Inductor, 6.7x3x6.7mm
22	Q1	1	40V	SQJ422EP-T1-GE3	Vishay-Siliconix	MOSFET, N-CH, 40 V, 75 A, PowerPAK_SO-8L	PowerPAK_SO-8L
23	Q2	1	-60V	SQJ461EP	Vishay-Siliconix	MOSFET, P-CH, -60 V, 30 A, PowerPAK_SO-8L	PowerPAK_SO-8L
24	Q3	1	60V	SQ2360EES-T1-GE3	Vishay-Siliconix	MOSFET, N/P-CH, 60 V, 4.4 A, SOT-23	SOT-23
25	R1, R5, R7, R11, R16, R18	6	0	CRCW06030000Z0EA	Vishay-Dale	RES, 0, 5%, 0.1 W, 0603	0603
26	R2, R3, R8, R10, R14, R19	6	100k	RT0603BRD07100KL	Yageo America	RES, 100 k, 0.1%, 0.1 W, 0603	0603
27	R6, R12	2	20.0k	CRCW060320K0FKEA	Vishay-Dale	RES, 20.0 k, 1%, 0.1 W, 0603	0603
28	R13	1	30.1	CRCW060330R1FKEA	Vishay-Dale	RES, 30.1, 1%, 0.1 W, 0603	0603
29	R17	1	2.00k	CPF0603B2K0E	TE Connectivity	RES, 2.00 k, 0.1%, 0.063 W, 0603	0603
30	U1, U3	2		LM53603AQPWPRQ1	Texas Instruments	5V/3.3V/ADJ, 3A, Buck Regulator For Automotive Applications, PWP0016H	PWP0016H
31	U2	1		LM74610QDQKGRQ1	Texas Instruments	Smart Diode Controller, DGK0008A	DGK0008A
32	U4	1		TLVH431ACDBVRA	Texas Instruments	Low-Voltage Adjustable Precision Shunt Regulator, 129 ppm / degC, 80 mA, 0 to 70 degC, 5-pin SOT-23 (DBV), Green (RoHS & no Sb/Br)	DBV0005A
33	C18, C34	0	DNP	Used in BOM report	Used in BOM report	CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageReference]	Used in PnP output and some BOM reports
34	FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial
35	R4, R15	0	DNP	Used in BOM report	Used in BOM report	RES, xxx ohm, x%, xW, [PackageReference]	Used in PnP output and some BOM reports
36	R9, R20	0	Value	Used in BOM report	Used in BOM report	RES, xxx ohm, x%, xW, [PackageReference]	Used in PnP output and some BOM reports

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